CM1242-33CP

1-Channel ESD Protection Device in 0201 CSP

Description

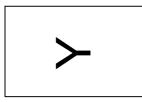
The CM1242–33CP is a 2–bump ESD protection device in 0201 CSP form factor. It is fully compliant with IEC 61000–4–2. The CM1242–33CP is also RoHS II compliant and has a pure tin finish.

Table 1. PIN DESCRIPTIONS

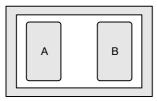
Pin	Description			
A	ESD Channel Pin 1			
В	ESD Channel Pin 2			

PACKAGE / PINOUT DIAGRAMS

Top View (Bumps Down)



Bottom View (Bumps Up)





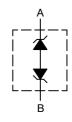
ON Semiconductor®

http://onsemi.com



WLCSP2 CP SUFFIX CASE 567AV





MARKING DIAGRAM



Y = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
CM1242-33CP	CSP (Pb-Free)	10,000/Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1242-33CP

SPECIFICATIONS

Table 2. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	–55 to +150	°C
Operating Temperature Range	-40 to +85	°C
Maximum Input Voltage	±5.5	V

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V _B	Breakdown Voltage	I _F = +10 mA I _F = -10 mA	6.0 -9.0	7.6 -7.6	9.0 -6.0	V
I _{LEAK}	Channel Leakage Current	V _{IN} = ±3.3 V		±0.1	±0.5	μA
C _{IN}	Channel Input Capacitance	At 1 MHz, V _{IN} = 0 V	45	55	66	pF
V _{ESD}	ESD Protection Peak Discharge Voltage at any channel input a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±30 ±30			kV
V _{CL}	Channel Clamp Voltage Positive Transients Negative Transients	I _{PP} = 1 A, t _p = 8/20 μs		+8.6 -8.6		V
R _{DYN}	Dynamic Resistance Positive Transients Negative Transients	I _{PP} = 1 A, t _p = 8/20 μs		0.4 0.4		Ω

1. $T_A = 25^{\circ}C$ unless otherwise specified. 2. Standard IEC 61000-4-2 with $C_{Discharge} = 150 \text{ pF}$, $R_{Discharge} = 330 \Omega$.

CM1242-33CP

MECHANICAL SPECIFICATIONS

CM1242-33CP Mechanical Specifications

The CM1242–33CP is supplied in a 2-bump Chip Scale Package (CSP). Dimensions are presented below.

Table 4. CSP TAPE AND REEL SPECIFICATIONS

Part Number	Chip Size (mm)	Pocket Size (mm) B ₀ X A ₀ X K ₀	Tape Width W	Reel Diameter	Qty per Reel	Po	P ₁
CM1242-33CP	0.60 X 0.30 X 0.275	0.67 X 0.37 X 0.35	8 mm	178 mm (7″)	10,000	4 mm	2 mm

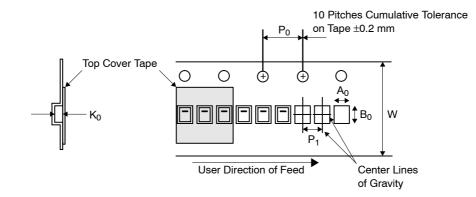
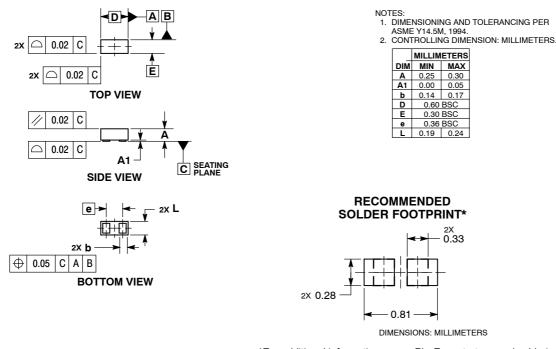


Figure 1. Tape and Reel Mechanical Data

PACKAGE DIMENSIONS

WLCSP2, 0.6x0.3 CASE 567AV ISSUE O



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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